REMARKS/ARGUMENTS

Favorable reconsideration of this application in light of the following discussion is respectfully requested.

Claims 1-20 are presently pending in this application.

In the outstanding Office Action, Claims 1-17 were rejected under 35 U.S.C. §102(b) as being anticipated by Azuma et al. (U.S. Publication 2004/0108862); and Claims 18-20 were rejected under 35 U.S.C. §102(b) as being anticipated by Azuma et al.

Briefly, Claim 1 is directed to a multilayer printed wiring board and recites "a core substrate; a first conductor layer having a plurality of conductor circuits formed on said core substrate; an interlayer insulating layer formed over said first conductor layer and said core substrate; a second conductor layer having a plurality of conductor circuits formed on said interlayer insulating layer; and a via hole structure electrically connecting one of said conductor circuits of said first conductor layer and one of said conductor circuits of said second conductor layer, wherein said first conductor layer on said core substrate has a thickness which is larger than a thickness of said second conductor layer on said interlayer insulating layer." Claim 6 is directed to a multilayer printed wiring board and recites "a core substrate comprising a multilayer core substrate comprising not less than three layers including at least one inner conductor layer having a plurality of conductor circuits; a conductor layer having a plurality of conductor circuits formed over said core substrate; an interlayer insulating layer formed over said conductor layer and said core substrate; and a through hole structure formed through said interlayer insulating layer and electrically connecting one of said conductor circuits of said at least one inner conductor layer and one of said conductor circuits of said conductor layer formed over said core substrate, wherein the at least one inner conductor layer of said core substrate and the conductor layer over said core substrate include a power supply layer or an earth."

The Office Action maintains that Claim 1 is anticipated by Azuma et al., asserting Figure 23 A of Azuma et al. discloses that "a thickness of the conductor layer (Figure 23 A Element 70 A2) on said core substrate (Figure 23 A Element 70 B2) is larger than a thickness of the conductor layer (Figure 23 A Element 70 A1) on the interlayer insulating layer (Figure 23 A Element 70 B1)."[1] However, Applicants respectfully submit that in Figure 23 A, Azuma et al. shows **interlayer insulating layers 70 A1, 70 A2, not conductor layers,** and according to Azuma et al., the layers made of conductive materials are represented by the transmission line 74_3 and the grounding line (ground layer) 76_3. Moreover, nowhere does Azuma et al. describe that the transmission line 74_3 be made thicker than the grounding line (ground layer) 76_3. Nor does Azuma et al. show the transmission line 74_3 being electrically connected to the grounding line (ground layer) 76_3 through a viahole connection. Accordingly, Azuma et al. clearly fails to teach "a first conductor layer ...; a second conductor layer ..., wherein said first conductor layer on said core substrate has a thickness which is larger than a thickness of said second conductor layer on said interlayer insulating layer" as recited in Claim 1 and "a core substrate comprising a multilayer core substrate comprising not less than three layers including at least one inner conductor layer having a plurality of conductor circuits ..., wherein the at least one inner conductor layer of said core substrate ... include[s] a power supply layer or an earth" as recited in Claim 6. Therefore, the structures recited in Claims 1 and 6 are clearly distinguishable from Azuma et al., and thus the first and second conductor layers as recited in Claim 1 and the core substrate as recited in Claim 6 are not anticipated by or rendered obvious over Azuma et al.

Likewise, Claim 18 recites "a multilayered structure formed on said core substrate and including a first conductor layer having a plurality of conductor circuits formed on said core substrate, at least one interlayer insulating layer formed over said first conductor layer,

[1] The Office Action, pages 8-9.

and a second conductor layer having a plurality of conductor circuits formed on said at least one interlayer insulating layer, wherein said first conductor layer on said core substrate has a thickness which is larger than a thickness of said second conductor layer on said at least one interlayer insulating layer" and is believed to include subject matter substantially similar to what is recited in Claim 1 to the extent discussed above. Thus, Claim 18 is also distinguishable from Azuma et al.

For the foregoing reasons, Claims 1, 6 and 18 are believed to be allowable. Furthermore, since Claims 2-5, 7-17, 19 and 20 depend directly or indirectly from one of Claims 1, 6 and 18, substantially the same arguments set forth above also apply to these dependent claims. Hence, Claims 2-5, 7-17, 19 and 20 are believed to be allowable as well.

In view of the discussions presented above, Applicants respectfully submit that the present application is in condition for allowance, and an early action favorable to that effect is earnestly solicited.

Respectfully submitted,

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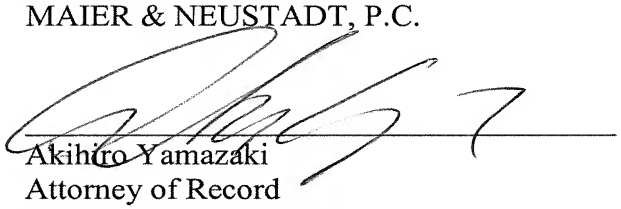

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